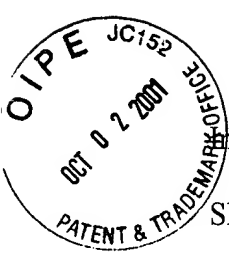


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IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

re application of:)
Shinji TAKEDA et al.) Atty. Docket No.: **TM&K0007**
Serial No. 09/785,436)
Filed: February 20, 2001) Group Art Unit: 2813
For: SEMICONDUCTOR DEVICE AND)
PROCESS FOR FABRICATION)
THEREOF) Examiner: S. GEYER
Date: October 2, 2001

SUPPLEMENTAL INFORMATION DISCLOSURE STATEMENT

Assistant Commissioner for Patents
Washington, D. C. 20231

Sir:

This is a Supplemental Information Disclosure Statement with regard to the above-identified application. Copies of the document listed in the attached Form PTO/SB/08A are attached.

Document A relates to a method of jointing an integrated circuit. Document B relates to a high heat-resistant resin-sealing type semiconductor device. Document C relates to an insulative paste. Document D relates to a resin-sealed semiconductor device. Document E relates to a conductive adhesive film, its production and adhesion method. Document F relates to an adhesive film, its production and method for adhesion. Document G relates to a die-bonding adhesive composition. Also attached are copies of two Office Actions (dated September 19, 2000 and

January 16, 2001), including an English translation of each, issued in a corresponding Japanese

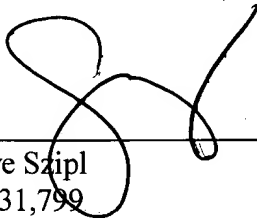
application. It is believed that the relevancy of each of these documents is quite clear from the discussion of the documents in said Japanese Office Actions. Accordingly, no further comment in regard to the disclosures of these documents is believed to be required.

It is respectfully requested that the attached documents be considered and officially cited, and that a copy of the Form PTO/SB/08A, initialed by the Examiner to indicate that the documents have been considered, be returned to the applicants.

It is believed that the present Information Disclosure Statement complies with the requirements of 37 C.F.R. §§ 1.97-8, and the undersigned's check for \$180.00 in payment of the fee for said Information Disclosure Statement is attached. The Commissioner is hereby authorized to deduct any additional fees required with this filing, or to credit any overpayment, to the undersigned's Deposit Account No. 50-1281.

Respectfully submitted,

GRIFFIN & SZIPL, PC



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